

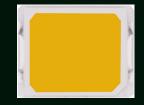
# Bridgelux® SMD 2835 1W 18V

Product Data Sheet DS253

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PXEN-27x| 30x| 35x| 40x| 50x| 57x| 65x

# SMD 2835



## Introduction

The Bridgelux SMD 2835 LED is hot-color targeted, which ensures that the LEDs fall within their specified color bin at the typical application conditions of 85°C. With its broad lumen coverage and wide range of CCT options, the SMD 2835 provides unparalleled design-in flexibility for indoor and outdoor lighting applications. The SMD 2835 is ideal as a drop-in replacement for emitters with an industry standard 2.8mm x 3.5mm footprint.

## Features

- Industry-standard 2835 footprint
- 9 bin color control
- Hot-color targeting ensures that color is within the ANSI bin at the typical application conditions of 85°C
- Enables 3- and 5-step MacAdam ellipse custom binning kits
- RoHS compliant and lead free
- Multiple CCT configurations for a wide range of lighting applications

#### Benefits

- · Lower operating and manufacturing cost
- Ease of design and rapid go-to-market
- Uniform, consistent white light
- · Reliable and constant white point
- Compliant with environmental standards
- Design flexibility

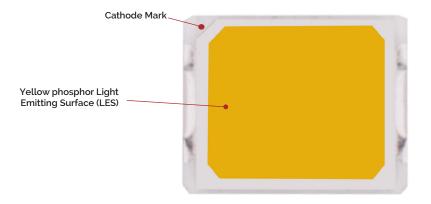


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# Product Feature Map

Bridgelux SMD LED products come in industry standard package sizes and follow ANSI binning standards. These LEDs are optimized for cost and performance, helping to ensure highly competitive system lumen per dollar performance while addressing the stringent efficacy and reliability standards required for modern lighting applications.



#### **Product Nomenclature** The part number designation for Bridgelux SMD 2835 is explained as follows: 8 9 10 11 12 13 14 15 16 17 1234 567 18 BXEN - 27 E – 1 2 H – 18 A -00-00-0 Product Family **Color Bin Options** └─ Forward Voltage Bins Nominal CCT 27 = 2,700K – Flux Bins 30 = 3,000K 35 = 3,500K 40 = 4,000K **Product Version** 50 = 5,000K Minimum CRI -Typical Forward Voltage 57 = 5,700K E = 80 CRI 65 = 6,500K G = 90 CRI High Power Die count in series Die count in parallel

#### **Product Test Conditions**

Bridgelux SMD 2835 LEDs are tested and binned with a 10ms pulse of 50mA at T<sub>j</sub> (junction temperature)=T<sub>sp</sub> (solder point temperature) =25°C. Forward voltage and luminous flux are binned at a T<sub>j</sub>=T<sub>sp</sub>=25°C, while color is hot targeted at a T<sub>sp</sub> of 85°C.

## Product Selection Guide

The following product configurations are available:

#### **Table 1:** Selection Guide, Pulsed Measurement Data at 50mA ( $T_i = T_{sp} = 25^{\circ}C$ )

				,	-1-					
Part Number <sup>16</sup>	Nominal CCT <sup>2</sup>	CRI <sup>3,5</sup>	Nominal Drive Current	Fo	orward Voltage (V)	9 <sup>4. 5</sup>	Typical Pulsed	Typical Power	Typical Efficacy (lm/W)	
	(K)		(mA)	Min	Typical	Max	- Flux (lm)⁴.⁵	(\\\/)	(lm/w)	
BXEN-27E-12H-18A-00-00-0	2700	80	50	17.0	18.1	19.0	131	0.9	145	
BXEN-27E-12H-18AE-00-00-0	2700	80	50	17.0	18.1	19.0	131	0.9	145	
BXEN-27G-12H-18A-00-00-0	2700	90	50	17.0	18.1	19.0	110	0.9	122	
BXEN-30E-12H-18A-00-00-0	3000	80	50	17.0	18.1	19.0	135	0.9	149	
BXEN-30G-12H-18A-00-00-0	3000	90	50	17.0	18.1	19.0	113	0.9	125	
BXEN-35E-12H-18A-00-00-0	3500	80	50	17.0	18.1	19.0	135	0.9	149	
BXEN-35G-12H-18A-00-00-0	3500	90	50	17.0	18.1	19.0	115	0.9	127	
BXEN-40E-12H-18A-00-00-0	4000	80	50	17.0	18.1	19.0	140	0.9	155	
BXEN-40G-12H-18A-00-00-0	4000	90	50	17.0	18.1	19.0	120	0.9	133	
BXEN-50E-12H-18A-00-00-0	5000	80	50	17.0	18.1	19.0	140	0.9	155	
BXEN-50G-12H-18A-00-00-0	5000	90	50	17.0	18.1	19.0	120	0.9	133	
BXEN-57E-12H-18A-00-00-0	5700	80	50	17.0	18.1	19.0	140	0.9	155	
BXEN-57G-12H-18A-00-00-0	5700	90	50	17.0	18.1	19.0	120	0.9	133	
BXEN-65E-12H-18A-00-00-0	6500	80	50	17.0	18.1	19.0	140	0.9	155	
BXEN-65E-12H-18AE-00-00-0	6500	80	50	17.0	18.1	19.0	140	0.9	155	
BXEN-65G-12H-18A-00-00-0	6500	90	50	17.0	18.1	19.0	120	0.9	133	

#### **Table 2:** Selection Guide, Pulsed Test Performance $(T_{so} = 85^{\circ}C)^{7.8}$

Part Number <sup>16</sup>	Part Number <sup>1.6</sup> Nominal CCT <sup>2</sup> CRI <sup>3.5</sup> Curre				orward Voltag (V)	e <sup>5</sup>	Typical Pulsed	Typical Power	Typical Efficacy	
	(K)		(mA)	Min	Typical	Max	Flux (lm)⁵	(\\\/)	(lm/W)	
BXEN-27E-12H-18A-00-00-0	2700	80	50	16.8	17.9	18.8	116	0.9	130	
BXEN-27E-12H-18AE-00-00-0	2700	80	50	16.8	17.9	18.8	116	0.9	130	
BXEN-27G-12H-18A-00-00-0	2700	90	50	16.8	17.9	18.8	98	0.9	109	
BXEN-30E-12H-18A-00-00-0	3000	80	50	16.8	17.9	18.8	120	0.9	134	
BXEN-30G-12H-18A-00-00-0	3000	90	50	16.8	17.9	18.8	100	0.9	112	
BXEN-35E-12H-18A-00-00-0	3500	80	50	16.8	17.9	18.8	120	0.9	134	
BXEN-35G-12H-18A-00-00-0	3500	90	50	16.8	17.9	18.8	102	0.9	114	
BXEN-40E-12H-18A-00-00-0	4000	80	50	16.8	17.9	18.8	124	0.9	139	
BXEN-40G-12H-18A-00-00-0	4000	90	50	16.8	17.9	18.8	106	0.9	119	
BXEN-50E-12H-18A-00-00-0	5000	80	50	16.8	17.9	18.8	124	0.9	139	
BXEN-50G-12H-18A-00-00-0	5000	90	50	16.8	17.9	18.8	106	0.9	119	
BXEN-57E-12H-18A-00-00-0	5700	80	50	16.8	17.9	18.8	124	0.9	139	
BXEN-57G-12H-18A-00-00-0	5700	90	50	16.8	17.9	18.8	106	0.9	119	
BXEN-65E-12H-18A-00-00-0	6500	80	50	16.8	17.9	18.8	124	0.9	139	
BXEN-65E-12H-18AE-00-00-0	6500	80	50	16.8	17.9	18.8	124	0.9	139	
BXEN-65G-12H-18A-00-00-0	6500	90	50	16.8	17.9	18.8	106	0.9	119	

Notes for Tables 1 & 2:

1. The last 7 characters (including hyphens '-') refer to flux bins, forward voltage bins, and color bin options, respectively. "00-00-0" denotes the full distribution of flux, forward voltage, and 7 SDCM color.

Example: BXEN-27E-12H-18A-00-00-0 refers to the full distribution of flux, forward voltage, and color within a 2700K 7-step ANSI standard chromaticity region with a minimum of 80CRI, 1x2 die configuration, high power, 18.1V typical forward voltage.

- 2. Product CCT is hot targeted at  $T_{sp}$  = 85°C. Nominal CCT as defined by ANSI C78.377-2011
- 3. Listed CRIs are minimum values and include test tolerance.
- 4. Products tested under pulsed condition (10ms pulse width) at nominal drive current where T<sub>i</sub>=T<sub>sn</sub>=25°C.
- 5. Bridgelux maintains a ±7.5% tolerance on luminous flux measurements, ±0.15V tolerance on forward voltage measurements, and ±2 tolerance on CRI measurements for the SMD 2835.
- 6. Refer to Table 5 and Table 6 for Bridgelux SMD 2835 Luminous Flux Binning and Forward Voltage Binning information.
- 7. Typical pulsed test performance values are provided as reference only and are not a guarantee of performance.
- 8. Typical performance is estimated based on operation under pulsed current with LED emitter mounted onto a heat sink with thermal interface material and the solder point temperature maintained at 85°C. Based on Bridgelux test setup, values may vary depending on the thermal design of the luminaire and/or the exposed environment to which the product is subjected.

# **Electrical Characteristics**

#### Table 3: Electrical Characteristics

	Drive Current	Fo	orward Voltag (V) <sup>2,3</sup>	је	Typical Temperature Coefficient	Typical Thermal Resistance	
Part Number <sup>1</sup>	(mA)	Minimum	Typical	Maximum	of Forward Voltage ∆V,∕∆T (mV/°C)	Junction to Solder Point⁴ R <sub>j-sp</sub> (°C∕W)	
BXEN-XXX-12H-18A-00-00-0	50	17.0	18.1	19.0	-4.02	16.5	

Notes for Tables 3:

1. The last 7 characters (including hyphens '-') refer to flux bins, forward voltage bins, and color bin options, respectively. "00-00-0" denotes the full distribution of flux, forward voltage, and 7 SDCM color.

Example: BXEN-27E-12H-18A-00-00-0 refers to the full distribution of flux, forward voltage, and color within a 2700K 7-step ANSI standard chromaticity region with a minimum of 80CRI, 1x2 die configuration, low power, 18.1V typical forward voltage.

2. Bridgelux maintains a tolerance of ± 0.15V on forward voltage measurements. Voltage minimum and maximum values at the nominal drive current are guaranteed by 100% test.

3. Products tested under pulsed condition (10ms pulse width) at nominal drive current where  $T_{so} = 25^{\circ}C$ .

4. Thermal resistance value was calculated using total electrical input power; optical power was not subtracted from input power.

5. Thermal resistance is only for the LED test values

# Absolute Maximum Ratings

#### Table 4: Maximum Ratings

Parameter	Maximum Rating				
LED Junction Temperature (T <sub>j</sub> )	125°C				
Storage Temperature	-40°C to +105°C				
Operating Solder Point Temperature ( $T_{sp}$ )	-40°C to +105°C				
Soldering Temperature	260°C or lower for a maximum of 10 seconds				
Maximum Drive Current	65mA				
Maximum Peak Pulsed Forward Current <sup>1</sup>	130mA				
Maximum Reverse Voltage <sup>2</sup>	-				
Moisture Sensitivity Rating	MSL 3				
Electrostatic Discharge	2kV HBM. JEDEC-JS-001-HBM and JEDEC-JS-001-2012				

Notes for Tables 4:

 Bridgelux recommends a maximum duty cycle of 10% and pulse width of 10 ms when operating LED SMD at maximum peak pulsed current specified. Maximum peak pulsed current indicate values where LED SMD can be driven without catastrophic failures.

2. Light emitting diodes are not designed to be driven in reverse voltage and will not produce light under this condition. no rating is provided

## **Product Bin Definitions**

Table 5 lists the standard photometric luminous flux bins for Bridgelux SMD 2835 LEDs. Although several bins are listed, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all CCTs.

Bin Code	Minimum	Maximum	Unit	Condition
5D	105	110		
5E	110	115		
5F	115	120		
5G	120	125		
5H	125	130	lm	I <sub>F</sub> =50mA
5J	130	135		
5K	135	140		
5L	140	145		
5M	145	150		

## **Table 5:** Luminous Flux Bin Definitions at 50mA, $T_{sp}$ =25°C

Note for Tables 5:

1. Bridgelux maintains a tolerance of ± 7.5% on luminous flux measurements.

## **Table 6:** Forward Voltage Bin Definition at 50mA, $T_{sp}$ =25°C

Bin Code	Minimum	Maximum	Unit	Condition	
Mı	17.0	17.5			
N1	17.5	18.0		L 50mA	
P1	18.0	18.5	V	I <sub>F</sub> =50mA	
Q1	18.5	19.0			

Note for Tables 6:

1. Bridgelux maintains a tolerance of ± 0.15V on forward voltage measurements.

## **Product Bin Definitions**

сст	Color Space	Cente	r Point	Major Axis	Minor Axis	Ellipse	Color Bin	
		Х	Y			Rotation Angle		
	3 SDCM	0.4578	0.4101	0.0081	0.0042	53.7	1	
2700K	5 SDCM	0.4578	0.4101	0.0135	0.007	53.7	A/B/C/D	
	3 SDCM	0.4630	0.4200	0.0081	0.0042	53.7	1	
2700K IEC	5 SDCM	0.4630	0.4200	0.0135	0.007	53.7	A/B/C/D	
	3 SDCM	0.4338	0.4030	0.00834	0.00408	53.22	1	
3000K	5 SDCM	0.4338	0.4030	0.01390	0.00680	53.22	A/B/C/D	
3500K	3 SDCM	0.4073	0.3917	0.00927	0.00414	54.00	1	
	5 SDCM	0.4073	0.3917	0.01545	0.00690	54.00	A/B/C/D	
	3 SDCM	0.3818	0.3797	0.00939	0.00402	53.72	1	
4000K	5 SDCM	0.3818	0.3797	0.01565	0.00670	53.72	A/B/C/D	
	3 SDCM	0.3447	0.3553	0.00822	0.00354	59.62	1	
5000K	5 SDCM	0.3447	0.3553	0.01370	0.00590	59.62	A/B/C/D	
	3 SDCM	0.3287	0.3417	0.00497	0.00213	59.09	1	
5700K	5 SDCM	0.3287	0.3417	0.01243	0.00533	59.09	A/B/C/D	
0	3 SDCM	0.3123	0.3282	0.00669	0.00285	58.57	1	
6500K	5 SDCM	0.3123	0.3282	0.01115	0.00475	58.57	A/B/C/D	
0	3 SDCM	0.3130	0.3170	0.00669	0.00285	58.57	1	
6500K IEC	5 SDCM	0.3130	0.3170	0.01115	0.00475	58.57	A/B/C/D	

## Table 7: 3- and 5-step MacAdam Ellipse Color Bin Definitions

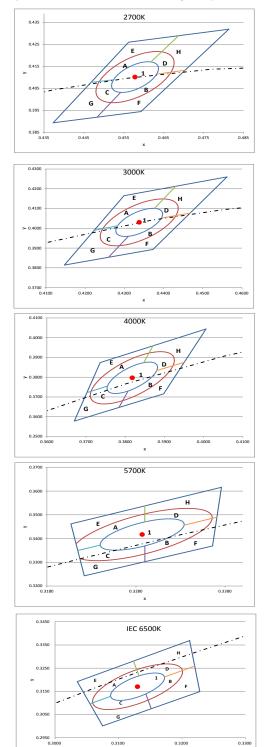
Point	270	ооК	2700	K IEC	300	ооК	350	оок	400	оок	500	ооК	579	оок	650	ооК	6500	K IEC	Color
Foint	x	У	x	У	x	У	x	У	x	У	x	У	x	У	x	У	x	у	Bin
	0.4813	0.4319	0.4865	0.4418	0.4562	0.4260	0.4299	0.4165	0.4006	0.4044	0.3551	0.3760	0.3376	0.3616	0.3205	0.3481	0.3212	0.3369	
ANSI	0.4562	0.426	0.4614	0.4359	0.4299	0.4165	0.3996	0.4015	0.3736	0.3874	0.3376	0.3616	0.3207	0.3462	0.3028	0.3304	0.3035	0.3192	
ANSI	0.4373	0.3893	0.4425	0.3992	0.4147	0.3814	0.3889	0.3690	0.3670	0.3578	0.3366	0.3369	0.3222	0.3243	0.3068	0.3113	0.3075	0.3001	
	0.4593	0.3944	0.4645	0.4043	0.4373	0.3893	0.4147	0.3814	0.3898	0.3716	0.3515	0.3487	0.3366	0.3369	0.3221	0.3261	0.3228	0.3149	F/F/
	0.4687	0.4289	0.4740	0.4389	0.4431	0.4213	0.4148	0.4090	0.3871	0.3959	0.3463	0.3687	0.3290	0.3538	0.3115	0.3391	0.3124	0.3281	G/H
V-up	0.4618	0.4170	0.4673	0.4268	0.4377	0.4101	0.4112	0.3996	0.3847	0.3873	0.3457	0.3617	0.3290	0.3470	0.3124	0.3328	0.3132	0.3217	,
	0.4483	0.3919	0.4535	0.4018	0.4260	0.3854	0.4018	0.3752	0.3784	0.3647	0.3440	0.3427	0.3290	0.3300	0.3144	0.3186	0.3152	0.3075	
V-down	0.4542	0.4031	0.4597	0.4130	0.4310	0.3960	0.4053	0.3844	0.3807	0.3730	0.3445	0.3495	0.3290	0.3369	0.3135	0.3250	0.3143	0.3139	
11 loft	0.4468	0.4077	0.4520	0.4176	0.4223	0.3990	0.3941	0.3848	0.3702	0.3722	0.3371	0.3490	0.3215	0.3350	0.3048	0.3207	0.3055	0.3097	
H-left	0.4524	0.4089	0.4577	0.4190	0.4283	0.4013	0.4012	0.3885	0.3755	0.3755	0.3395	0.3509	0.3240	0.3372	0.3081	0.3240	0.3088	0.3129	
Livialat	0.4703	0.4132	0.4755	0.4231	0.4468	0.4077	0.4223	0.3990	0.3950	0.3875	0.3533	0.3620	0.3371	0.3490	0.3213	0.3373	0.3220	0.3259	
H-right	0.4632	0.4115	0.4685	0.4215	0.4394	0.4052	0.4133	0.3945	0.3880	0.3834	0.3498	0.3592	0.3334	0.3456	0.3165	0.3325	0.3172	0.3212	
Center	0.4578	0.4101	0.4630	0.4200	0.4338	0.4030	0.4073	0.3917	0.3818	0.3797	0.3447	0.3553	0.3287	0.3417	0.3123	0.3282	0.3130	0.3170	

Notes for Tables 7:

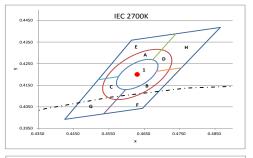
1. Color binning at  $T_{so}$ =85°C unless otherwise specified

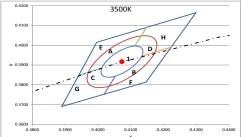
2. Bridgelux maintains a tolerance of ± 0.007 on x and y color coordinates in the CIE 1931 color space.

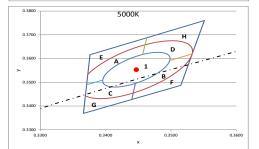
## **Product Bin Definitions**

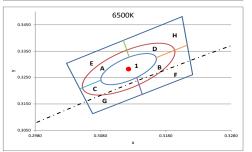












## Performance Curves

## Figure 2: Drive Current vs. Voltage (T<sub>sp</sub>=25°C)

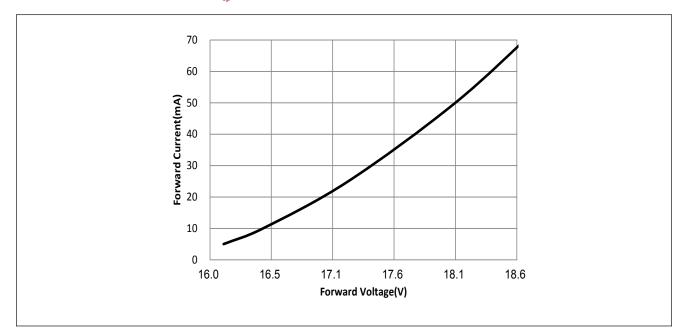
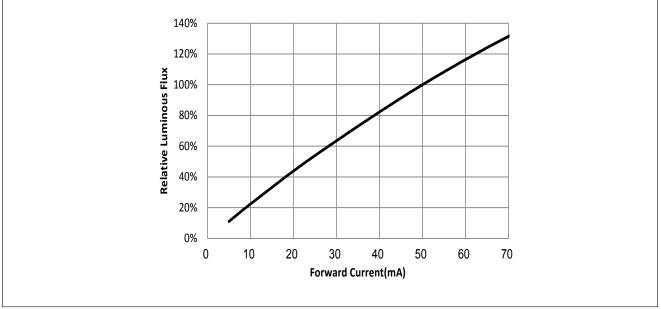


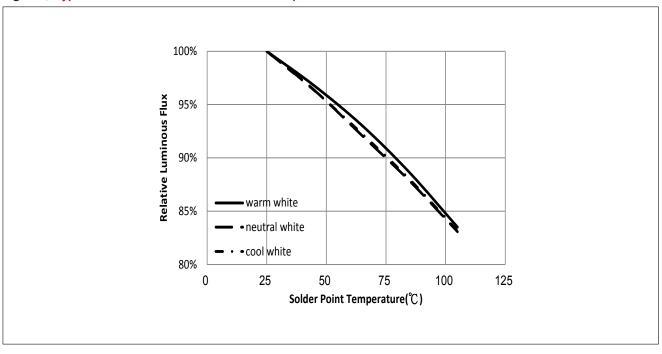
Figure 3: Typical Relative Luminous Flux vs. Drive Current (T<sub>sp</sub>=25°C)



Note for Figure 3:

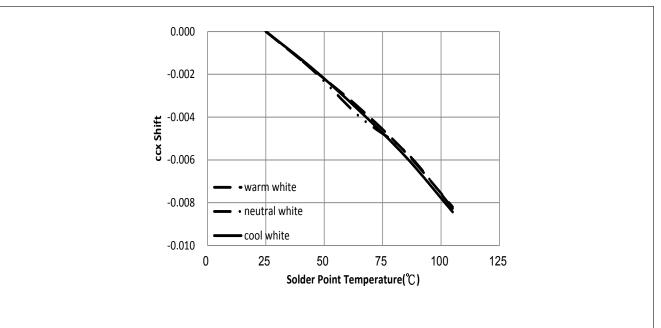
1. Bridgelux does not recommend driving high power LEDs at low currents. Doing so may produce unpredictable results. Pulse width modulation (PWM) is recommended for dimming effects.

## Performance Curves



#### Figure 4: Typical Relative Flux vs. Solder Point Temperature

Figure 5: Typical ccx Shift vs. Solder Point Temperature



Notes for Figures 4 & 5:

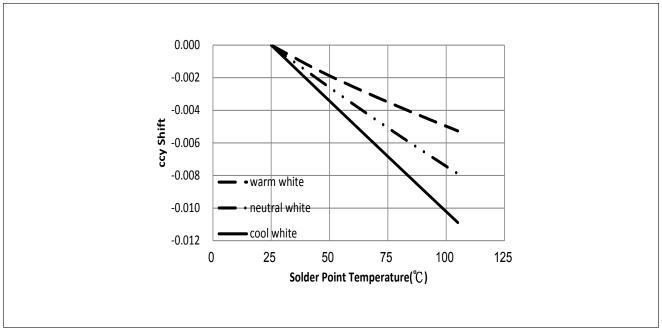
1. Characteristics shown for warm white based on 2700K and 80 CRI.

2. Characteristics shown for neutral white based on 4000K and 80 CRI.

3. Characteristics shown for cool white based on 5000K and 80 CRI.

4. For other color SKUs, the shift in color will vary. Please contact your Bridgelux Sales Representative for more information.

## Performance Curves



## Figure 6: Typical ccy Shift vs. Solder Point Temperature

Notes for Figure 6:

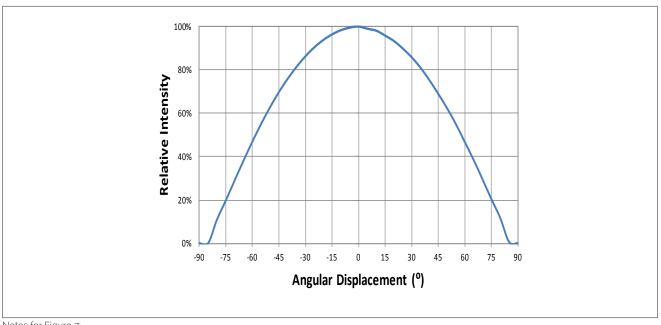
1. Characteristics shown for warm white based on 2700K and 80 CRI.

2. Characteristics shown for neutral white based on 4000K and 80 CRI.

3. Characteristics shown for cool white based on 5000K and 80 CRI.

4. For other color SKUs, the shift in color will vary. Please contact your Bridgelux Sales Representative for more information.

## **Typical Radiation Pattern**



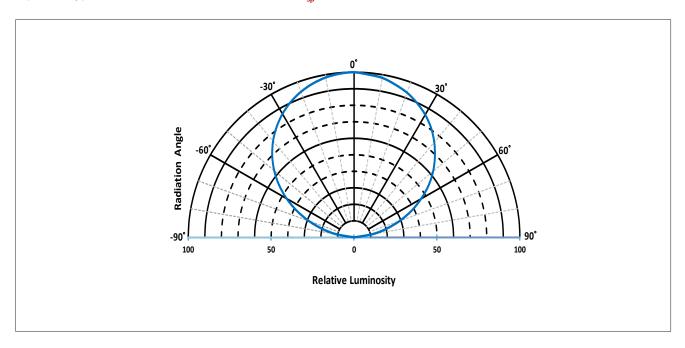
## Figure 7: Typical Spatial Radiation Pattern at 50mA, T<sub>sp</sub>=25°C

Notes for Figure 7:

1. Typical viewing angle is 120°.

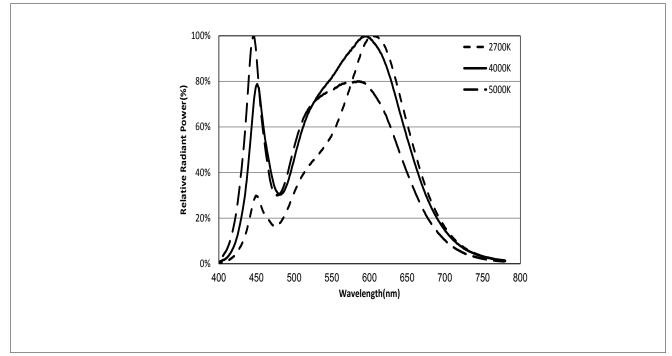
2. The viewing angle is defined as the off axis angle from the centerline where luminous intensity (Iv) is  $\frac{1}{2}$  of the peak value.

## Figure 8: Typical Polar Radiation Pattern at 50mA, T<sub>sp</sub>=25°C



# Typical Color Spectrum

## Figure 9: Typical Color Spectrum



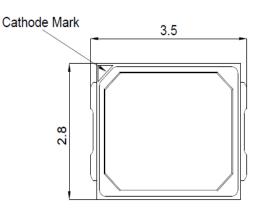
Notes for Figure 9:

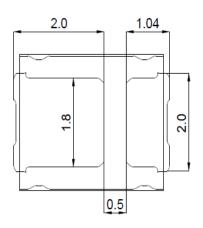
1. Color spectra measured at nominal current for Tsp = 25  $^\circ\mathrm{C}$ 

2. Color spectra shown for 80 CRI products.

## **Mechanical Dimensions**

## Figure 10: Drawing for SMD 2835











Notes for Figure 10:

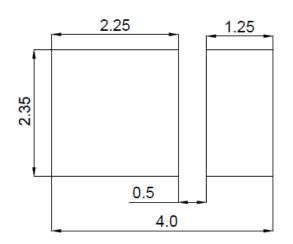
1. Drawings are not to scale.

2. Drawing dimensions are in millimeters.

3. Different mould pattern differences may.

3. Unless otherwise specified, tolerances are ± 0.10mm.

## Recommended PCB Soldering Pad Pattern



# Reliability

### Table 8: Reliability Test Items and Conditions

No .	Items	Reference Standard	Test Conditions	Drive Current	Test Duration	Units Failed/Tested
1	Moisture/Reflow Sensitivity	J-STD-020E	T <sub>std</sub> = 260°C, 10sec, Precondition: 60°C, 60%RH, 168hr	-	3 reflows	0/22
2	Low Temperature Storage	JESD22-A119	T <sub>a</sub> =-40°C	-	1000 hours	0/22
3	High Temperature Storage	JESD22-A103D	T <sub>a</sub> = 105°C	-	1000 hours	0/22
4	Low Temperature Operating Life	JESD22-A108D	T <sub>a</sub> =-40°C	50mA	1000 hours	0/22
5	Temperature Humidity Operating Life	JESD22-A101C	T <sub>sp</sub> =85°C, RH=85%	50mA	1000 hours	0/22
6	High Temperature Operating Life	JESD22-A108D	T <sub>sp</sub> =105 <sup>°</sup> C	65mA	1000 hours	0/22
7	Power switching	vitching IEC62717:2014 $T_{sp} = 105^{\circ}C$ 30 sec on, 30 sec off		65mA	30000 cycles	0/22
8	Thermal Shock	JESD22-A106B	T <sub>a</sub> =-40°C ~100°C; Dwell : 15min; Transfer: 10sec	-	200 cycles	0/22
9	Temperature Cycle	JESD22-A104E	T <sub>a</sub> =-40°C ~100°C; Dwell at extreme temperature: 15min; Ramp rate < 105°C/min	-	200 cycles	0/22
10	Electrostatic Discharge	JS-001-2012	HBM, 2KV, 15kΩ, 100pF, Alternately positive or negative	-	-	0/22

## **Passing Criteria**

Item	Symbol	Test Condition	Passing Criteria
Forward Voltage	Vf	50mA	ΔVf<10%
Luminous Flux	Fv	50mA	<b>Δ</b> Fv<30%
Chromaticity Coordinates	(x, y)	50mA	Δu'v'<0.007

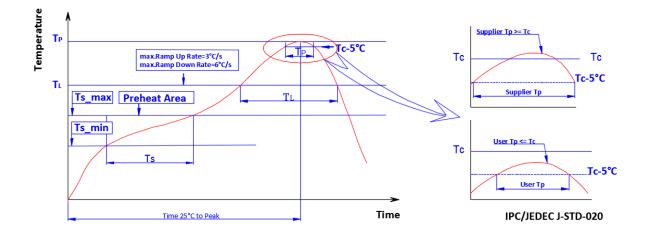
Notes for Tables 8:

1. Measurements are performed after allowing the LEDs to return to room temperature

2.  $T_{sid}$  : reflow soldering temperature;  $T_a$  : ambient temperature

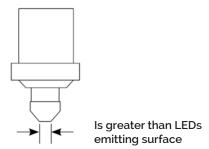
## **Reflow Characteristics**

#### Figure 11 : Reflow Profile



Profile Feature	Lead Free Assembly			
Temperature Min. (Ts_min)	160°C			
Temperature Max. (Ts_max)	205°C			
Time (ts) from Ts_min to Ts_max	60-150 seconds			
Ramp-Up Rate (TL to Tp)	3 °C/second			
Liquidus Temperature (TL)	220 °C			
Time (TL) Maintained Above TL	60-150 seconds			
Peak Temp( Tp)	260 °C max.			
Time (Tp) Within 5 $^\circ \rm C$ of the Specified Classification Temperature (Tc)	25 seconds max.			
Ramp-Down Rate (Tp to TL)	5 °C/second max.			
Time 25 °C to Peak Temperature	10 minutes max.			

## Figure 12 : Pick and Place

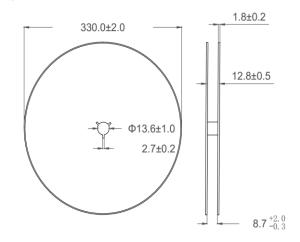


Note for Figure 12:

1. When using a pick and place machine, choose a nozzle that has a larger diameter than the LED's emitting surface. Using a Pick-and-Place nozzle with a smaller diameter than the size of the LEDs emitting surface will cause damage and may also cause the LED to not illuminate.

## Packaging

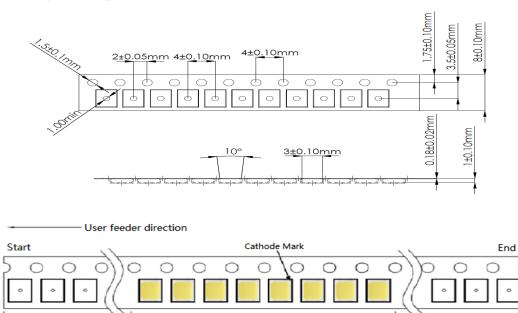
#### Figure 13: Emitter Reel Drawings



Note for Figure 13:

1. Drawings are not to scale. Drawing dimensions are in millimeters.

## Figure 14: Emitter Tape Drawings



Capacity per reel

( 17000 pcs LEDs)

Note for Figure 14:

1. Drawings are not to scale. Drawing dimensions are in millimeters.

With the seal portion is not

less than 400 mm spaces

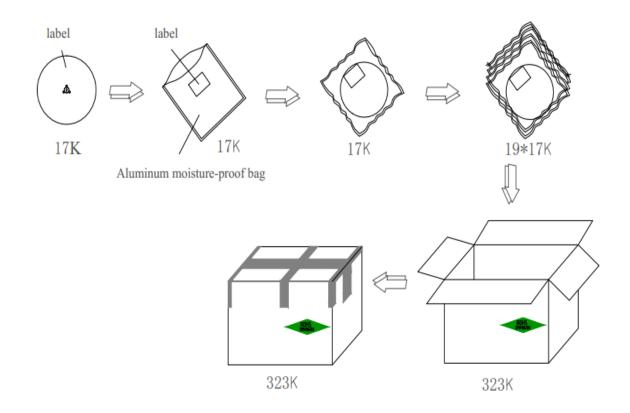
Leader

With the seal portion is not

End

less than 200 mm spaces

# Packaging



## Figure 15: Emitter Reel Packaging Drawings

Note for Figure 15:

1. Drawings are not to scale.

# Design Resources

Please contact your Bridgelux sales representative for assistance.

## Precautions

#### CAUTION: CHEMICAL EXPOSURE HAZARD

Exposure to some chemicals commonly used in luminaire manufacturing and assembly can cause damage to the LED emitter. Please consult Bridgelux Application Note AN51 for additional information.

#### CAUTION: EYE SAFETY

Eye safety classification for the use of Bridgelux SMD LED emitter is in accordance with IEC specification EN62471: Photobiological Safety of Lamps and Lamp Systems. SMD LED emitters are classified as Risk Group 1 when operated at or below the maximum drive current. Please use appropriate precautions. It is important that employees working with LEDs are trained to use them safely.

#### CAUTION: RISK OF BURN

Do not touch the SMD LED emitter during operation. Allow the emitter to cool for a sufficient period of time before handling. The SMD LED emitter may reach elevated temperatures such that could burn skin when touched.

## CAUTION

#### CONTACT WITH LIGHT EMITTING SURFACE (LES)

Avoid any contact with the LES. Do not touch the LES of the emitter or apply stress to the LES (yellow phosphor resin area). Contact may cause damage to the emitter

Optics and reflectors must not be mounted in contact with the LES (yellow phosphor resin area).

## Disclaimers

#### MINOR PRODUCT CHANGE POLICY

The rigorous qualification testing on products offered by Bridgelux provides performance assurance. Slight cosmetic changes that do not affect form, fit, or function may occur as Bridgelux continues product optimization.

## STANDARD TEST CONDITIONS

Unless otherwise stated, LED emitter testing is performed at the nominal drive current.

# About Bridgelux: Bridging Light and Life™

At Bridgelux, we help companies, industries and people experience the power and possibility of light. Since 2002, we've designed LED solutions that are high performing, energy efficient, cost effective and easy to integrate. Our focus is on light's impact on human behavior, delivering products that create better environments, experiences and returns—both experiential and financial. And our patented technology drives new platforms for commercial and industrial luminaires.

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